



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Patent Application of	)	Art Unit: 2822
Shunpei YAMAZAKI et/al.	)	Examiner: M. Wilczewski
Śerial No. 08/691,434√	)	CERTIFICATE OF MAILING
Filed: August 2, 1996	)	I hereby certify that this correspondence is being deposited with
For: METHOD OF FABRICATING	The United States Postal Service with sufficient postage	The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents,
SEMICONDUCTOR DEVICES AND	)	Washington, D.C. 20231, on 2 3
APPARATUS FOR PROCESSING A	)	
SEMICONDUCTOR	)	

## PRELIMINARY AMENDMENT

Honorable Commissioner of Patents Washington, D.C. 20231

Sir:

In response to the Office Action dated August 13, 2002 please amend the aboveidentified application as follows:

## IN THE CLAIMS:

Please cancel claims 76-77, 79, 84-85 and 90-91 and amend claims 16, 56, and 74-75 as follows:

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(Amended) An apparatus for processing a semiconductor comprising: a first vacuum chamber;

an ion introducing apparatus for doping a semiconductor layer formed over a substrate with a dopant impurity through an insulating film comprising oxide provided over said semiconductor layer;

an etching apparatus for etching said insulating film comprising oxide to expose a surface of said semiconductor layer, said etching apparatus connected to said ion introducing apparatus through said first vacuum chamber;

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